IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An exposure device exposing an exposure pattern to a substrate, comprising:

detecting means for detecting undulation or thickness unevenness each extending in a first direction on a surface of a substrate;

retaining means for supporting the substrate, the retaining means including,

~~having~~ support mechanisms configured to be elongated in a second direction orthogonal to [[a]] the first direction of the undulation or thickness unevenness detected by the detecting means, ~~for supporting the substrate~~[[,]] the support mechanisms being arranged in the first direction of the undulation or thickness unevenness, and

support mechanism adsorbing plates ~~capable of being~~ configured to be independently displaced in a third direction of displacement orthogonal to the surface of the substrate; and

a plurality of adsorbing means for adsorbing and retaining the substrate provided on the retaining means of the support mechanisms along a length direction of the support mechanisms[[,]] ~~for adsorbing and retaining the substrate~~.

Claim 2 (Currently Amended): The exposure device according to claim 1, wherein the support mechanisms comprise any of piezoelectric elements whose displacement amount along [[the]] a direction of displacement can be varied, displacement mechanisms using an air pressure, and motor drive mechanisms.

Claim 3 (Original): The exposure device according to claim 2, wherein the support mechanisms are linear or one-dimensional members.

Claim 4 (Currently Amended): The exposure device according to claim 1, wherein a [[size]] length of the retaining means ~~is equal to a size of the substrate or a length of a direction orthogonal to a direction of the undulation or thickness unevenness on the substrate~~

~~is equal or greater~~ extending along the first direction is greater than or equal to a length of the substrate in the first direction.

Claim 5 (Original): The exposure device according to claim 1, wherein the adsorbing means comprise any of suction means, vacuum suction means, and electrostatic chucks.

Claim 6 (Original): The exposure device according to claim 5, wherein an adsorbing force of the adsorbing means can be varied in accordance with magnitude of the undulation or thickness unevenness on the substrate.

Claim 7 (Original): The exposure device according to claim 1, wherein the detecting means receive a reflected beam of light applied to the surface of the substrate and measure the undulation or thickness unevenness on the surface of the substrate.

Claim 8 (Original): The exposure device according to claim 1, wherein the support mechanisms of the retaining means are arranged at an interval of a half of or smaller than a fundamental cycle of the undulation or thickness unevenness on the substrate.

Claim 9 (Original): The exposure device according to claim 1, further comprising elastic members provided on sides of the adsorbing means which are in contact with the substrate.

Claim ~~10~~ 11 (Currently Amended): A device for processing a member on a stage, comprising:

detecting means for detecting undulation or thickness unevenness in a first direction on a surface of a member;

retaining means for supporting the member, the retaining means including,

~~having~~ adsorbing plates configured to be elongated in a direction orthogonal to [[a]] the first direction of the undulation or thickness unevenness on the surface of the member, the adsorbing plates configured to be ~~being~~ aligned in the first direction of the undulation or thickness unevenness, the adsorbing plates configured to be ~~capable of being~~ independently displaced in a third direction of displacement orthogonal to the surface of the member; and

adsorbing means ~~provided on the respective adsorbing plates~~[[,]] for adsorbing the member, provided on the respective adsorbing plates.

Claim 11 (Withdrawn): A method of exposing an exposure pattern to a substrate provided at a predetermined position of retaining means in which a plurality of adsorbing plates are aligned,

the method comprising positioning and arranging the substrate on the retaining means, and exposing the pattern such that a direction orthogonal to a direction of undulation or thickness unevenness on a surface of the substrate corresponds to a direction of longitudinal edges of the adsorbing plates.

Claim 12 (Withdrawn): The exposure method according to claim 11, wherein the substrate provided on the retaining means is adsorbed by all of the adsorbing plates opposite to the substrate, and each of the adsorbing plates is displaced in a direction orthogonal to the surface of the substrate such that waviness on an exposed surface of the substrate fall in a predetermined range, before the exposure pattern is exposed.

Claim 13 (Withdrawn): The exposure method according to claim 11, wherein, of the plurality of adsorbing plates, an arbitrary number of the adsorbing plates corresponding to a predetermined exposed area on the surface of the substrate are operated to adsorb the substrate, and each of the adsorbing plates is displaced in a direction orthogonal to the surface of the substrate such that waviness on an exposed surface of the substrate fall in a predetermined range, before the exposure pattern is exposed.

Claim 14 (Withdrawn): A method of exposing an exposure pattern to a substrate provided at a predetermined position of retaining means in which a plurality of adsorbing plates are aligned, the method comprising:

adsorbing the substrate on surface of the adsorbing plates;

detecting undulation or thickness unevenness on a surface of the substrate; and

adjusting the adsorbing plates elongated in a direction orthogonal to a direction of the undulation or thickness unevenness, in a direction orthogonal to the surface of the substrate, in accordance with the detected undulation or thickness unevenness.

Claim 15 (Withdrawn): The exposure method according to claim 14, wherein adjusting the adsorbing plates displaces the substrate in the direction orthogonal to the surface of the substrate, such that waviness on the surface of the substrate fall in a predetermined range.

Claim 16 (Withdrawn): The exposure method according to claim 14, wherein adjusting the adsorbing plates displaces the substrate in the direction orthogonal to the surface of the substrate, such that waviness on the surface of the substrate one-dimensionally fall in a predetermined range.

Claim 17 (Withdrawn): A method for producing a thin film transistor by exposing a MOS-TFT pattern to a substrate provided at a predetermined position of retaining means at which a plurality of adsorbing plates are aligned, the method comprising:

adsorbing the substrate on surface of the adsorbing plates;

detecting undulation or thickness unevenness on a surface of the substrate;

adjusting the adsorbing plates elongated in a direction orthogonal to a direction of the undulation or thickness unevenness, in a direction orthogonal to the surface of the substrate, in accordance with the detected undulation or thickness unevenness; and

exposing a predetermined exposure pattern to the substrate on which a semiconductor thin film is preliminarily formed, by an exposure section, under a condition that the adsorbing plates are adjusted in accordance with the detected undulation or thickness unevenness.

Claim 18 (Withdrawn): The method according to claim 17, wherein the MOS-TFT pattern is exposed under a condition that the undulation or thickness unevenness on the surface of the substrate is managed in a range of DOF of an image-forming optical system during the adjustment of the adsorbing plates.

Claim 19 (Withdrawn): The method according to claim 17, further comprising forming a thin film transistor by exposing the predetermined exposure pattern to the semiconductor thin film formed on the substrate.

Claim 20 (Withdrawn): A method for producing a display device, comprising:

adsorbing the substrate on surface of the adsorbing plates;

detecting undulation or thickness unevenness on a surface of the substrate;

adjusting the adsorbing plates elongated in a direction orthogonal to a direction of the undulation or thickness unevenness, in a direction orthogonal to the surface of the substrate, in accordance with the detected undulation or thickness unevenness;

exposing a predetermined exposure pattern to the substrate on which a semiconductor thin film is preliminarily formed, by an exposure section, under a condition that the adsorbing plates are adjusted in accordance with the detected undulation or thickness unevenness; and

providing a preliminarily formed substrate to be opposite to the exposed substrate and arranging an electrooptic substance of a predetermined thickness between the substrates.

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Claim ~~21~~ (New): An exposure device exposing an exposure pattern to a substrate, comprising:

detecting means for detecting undulation or thickness unevenness each extending in a first direction on a surface of a substrate;

retaining means for supporting the substrate, the retaining means including,

support mechanisms configured to be elongated in a second direction orthogonal to the first direction of the undulation or thickness unevenness, and

support mechanism adsorbing plates configured to be independently displaced in a third direction of displacement orthogonal to the surface of the substrate; and

a plurality of adsorbing means for adsorbing and retaining the substrate provided on the retaining means of the support mechanisms along a length direction of the support mechanisms.

Claim ~~22~~ 13 (New): The exposure device of claim ~~21~~ 12, wherein the support mechanism adsorbing plates are displaced in the third direction in accordance with the detection of the detecting means.

Claim ~~23~~ 10 (New): The exposure device of claim 1, wherein a length of the retaining means extending along the second direction is greater than or equal to a length of the substrate in the second direction.